



AXIOMTEK

Q7M120

**Freescale i.MX6 Series ARM-based
Qseven System-on-Module**

Hardware User's Manual



Disclaimers

This manual has been carefully checked and believed to contain accurate information. Axiomtek Co., Ltd. assumes no responsibility for any infringements of patents or any third party's rights, and any liability arising from such use.

Axiomtek does not warrant or assume any legal liability or responsibility for the accuracy, completeness or usefulness of any information in this document. Axiomtek does not make any commitment to update the information in this manual.

Axiomtek reserves the right to change or revise this document and/or product at any time without notice.

No part of this document may be reproduced, stored in a retrieval system, or transmitted, in any form or by any means, electronic, mechanical, photocopying, recording, or otherwise, without the prior written permission of Axiomtek Co., Ltd.

CAUTION

If you replace wrong batteries, it causes the danger of explosion. It is recommended by the manufacturer that you follow the manufacturer's instructions to only replace the same or equivalent type of battery, and dispose of used ones.

©Copyright 2015 Axiomtek Co., Ltd.

All Rights Reserved

July 2015, Version A3

Printed in Taiwan

ESD Precautions

Computer boards have integrated circuits sensitive to static electricity. To prevent chipsets from electrostatic discharge damage, please take care of the following jobs with precautions:

- Do not remove boards or integrated circuits from their anti-static packaging until you are ready to install them.
- Before holding the board or integrated circuit, touch an unpainted portion of the system unit chassis for a few seconds. It discharges static electricity from your body.
- Wear a wrist-grounding strap, available from most electronic component stores, when handling boards and components.

Trademarks Acknowledgments

Axiomtek is a trademark of Axiomtek Co., Ltd.

IBM, PC/AT, PS/2, VGA are trademarks of International Business Machines Corporation.

ARM is a trademark of ARM Ltd.

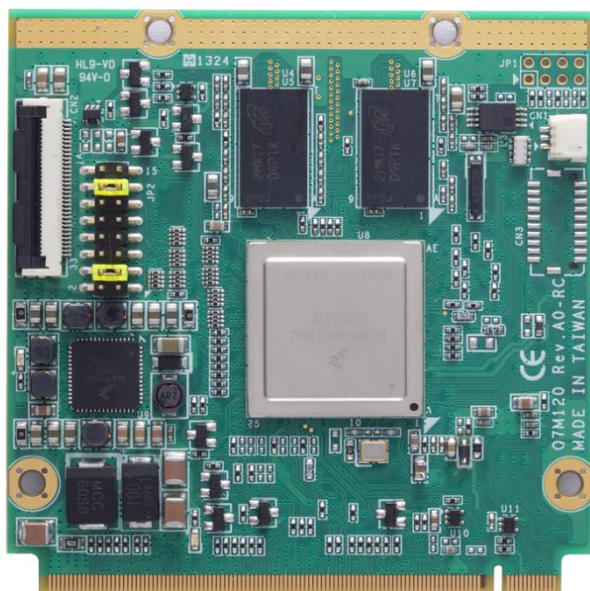
Other brand names and trademarks are the properties and registered brands of their respective owners.

Table of Contents

| | |
|---|----------|
| Disclaimers..... | ii |
| ESD Precautions..... | iii |
| Chapter 1 Introduction..... | 1 |
| 1.1 Features..... | 2 |
| 1.2 Specifications..... | 3 |
| Chapter 2 Board and Pin Assignments..... | 5 |
| 2.1 Board Dimensions and Fixing Holes..... | 5 |
| 2.2 Board Layout..... | 6 |
| 2.3 Installing Heatsink & Heatspreader..... | 7 |
| 2.3.1 Heatsink..... | 7 |
| 2.3.2 Heatspreader..... | 7 |
| 2.4 Connectors..... | 8 |
| 2.4.1 Boot Mode Selection (JP2)..... | 8 |
| 2.5 Connectors..... | 9 |
| 2.5.1 Debug Port Connector (CN1)..... | 9 |
| 2.5.2 33-pin ZIF Connector (CN2)..... | 9 |
| 2.5.3 JTAG Connector (JP1)..... | 10 |
| 2.5.4 20-pin Connector (CN3)..... | 10 |

Chapter 1

Introduction



The Q7M120 is a new Qseven module to support Freescale i.MX6series SoCs. It integrates system memory, storage as eMMC/SDHC socket, TTL LCD, audio, USB host/client, UARTs, CANBus and various I/O features. Taking the low power consumption advantages of ARM RISC architecture, the Q7M120 is extremely suitable to be deployed in the deeply embedded applications; such as HMI, data logger, extended temperature embedded controllers, etc.

1.1 Features

- Freescale i.MX6 family SoC information:

| Feature | i.MX6Quad(1.2GHz) | i.MX6DualLite(800MHz) | i.MX6Solo(800MHz) |
|-----------------------|---|---|---|
| On-chip RAM | DDR3 1066MHz 1GB | DDR3 800MHz 1GB | DDR3 800MHz 512MB |
| Memory I/F | eMMC NAND Flash 1GB | eMMC NAND Flash 1 GB | eMMC NAND Flash 1 GB |
| Touchscreen | No | No | No |
| Ethernet | x1 | x1 | x1 |
| Display | LVDS x1 24-bit TTL LCD HDMI x1 | LVDS x1 24-bit TTL LCD HDMI x1 | LVDS x1 24-bit TTL LCD HDMI x1 |
| Storage | SATA x1 SD/SDHC x2 | SD/SDHC x2 | SD/SDHC x2 |
| USB 2.0 | OTG HS with HS PHY x1 HS Host with HS PHY x1 | OTG HS with HS PHY x1 HS Host with HS PHY x1 | OTG HS with HS PHY x1 HS Host with HS PHY x1 |
| CAN | x2 | x2 | x2 |
| JTAG | x1 | x1 | x1 |
| SPI | x1 | x1 | x1 |
| I2C | x3 | x3 | x3 |
| UART | RS-232 x4 | RS-232 x4 | RS-232 x4 |
| GPIO (w/ LED) | x8 | x8 | x8 |
| Audio | Earphone x1 Line out x1 Mic-in x1 | Earphone x1 Line out x1 Mic-in x1 | Earphone x1 Line out x1 Mic-in x1 |
| System Control | Buttons x2 (Power,Reset,) Touch Panel Wafer x1 | Buttons x2 (Power,Reset,) Touch Panel Wafer x1 | Buttons x2 (Power,Reset,) Touch Panel Wafer x1 |
| Power | DC 5V, 5A CR2032 for Standby Power | DC 5V, 5A CR2032 for Standby Power | DC 5V, 5A CR2032 for Standby Power |

- Onboard DDR3-1066 memory 1GB supports up to 2GB capacity
- Onboard eMMC flash as booting device
- 24-bit TTL LCD
- One USB 2.0 ports and One MicroUSB OTG port
- One 10/100/1000 Base-T Ethernet
- One 100/10 Base-T Ethernet
- IIS Audio

1.2 Specifications

- **CPU**
 - Freescale i.MX6 series SoC; default is i.MX6Q
 - ARM Cortex A9™ CPU running at 1.2GHz.
 - 256KB integrated low power on-chip SRAM.
 - 64KB integrated mask-programmable on-chip ROM.
- **Boot ROM**
 - Linux kernel 3.0.35 compliant Android 4.3.1
(Please contact your agent for detail shipping content).
- **System Memory**
 - 1GB Maximum up to 2GB DDR3-1066 memory.
- **USB Interface**
 - One USB 2.0 ports and One MicroUSB OTG port OTG comply with USB Spec. Rev. 2.0.
- **Storage Interface**
 - One eMMC NAND flash chip on module; default is 4GB.
 - One SATA Connector on base serial-ATA to interface with hard disk drives.
 - One SD/SDHC Connector on base with up to 32GB capacity.
 - One Micro SD Connector on base with up to 32GB capacity
- **Display**
 - Two LVDS channels, connectivity to displays with LVDS interface.
 - One parallel display ports, RGB Data of 18 or 24 bits.
 - One HDMI with up to 1920x1080 resolution.
- **Ethernet**
 - One 10/100/1000 Base-T with Freescale i.MX6 integrated MAC and Atheros AR8031 PHY, support IEEE std 1588-compatible hardware timestamp.
 - One 10/100 Base-T with AX88772B
 - Compatible with IEEE std 802.3.
- **Audio**
 - Freescale IIS SGTL5000 codec for MIC-in/headphone via Qseven MXM interface.
- **Serial Port**
 - Four RS-232, with 4-wire
- **CANBus**
 - Two 2.0B protocol-compatible Controller Area Network (CAN) via Qseven MXM interface.
- **I²C**
 - Three I²C Master/Slave interfaces (up to 400kbps) connected to Qseven MXM interface.

- **SPI**
 - One SPI channel for 2 chip select via Qseven MXM interface.
- **GPIO**
 - Eight GPIO interfaces (up to 400kbps) via Qseven MXM interface with buttons.
- **Power**
 - +5V \pm 5% DC-in.
- **Form Factor**
 - 70mm x 70mm.
 - Thickness as 1.2mm \pm 0.1mm.
 - Qseven specifications v2.0 compliant.
- **Environments**
 - Operating temperature with Imx6: -40 ~ 85°C
 - Operating humidity: 10% RH ~ 85% RH relative humidity, non-condensing.

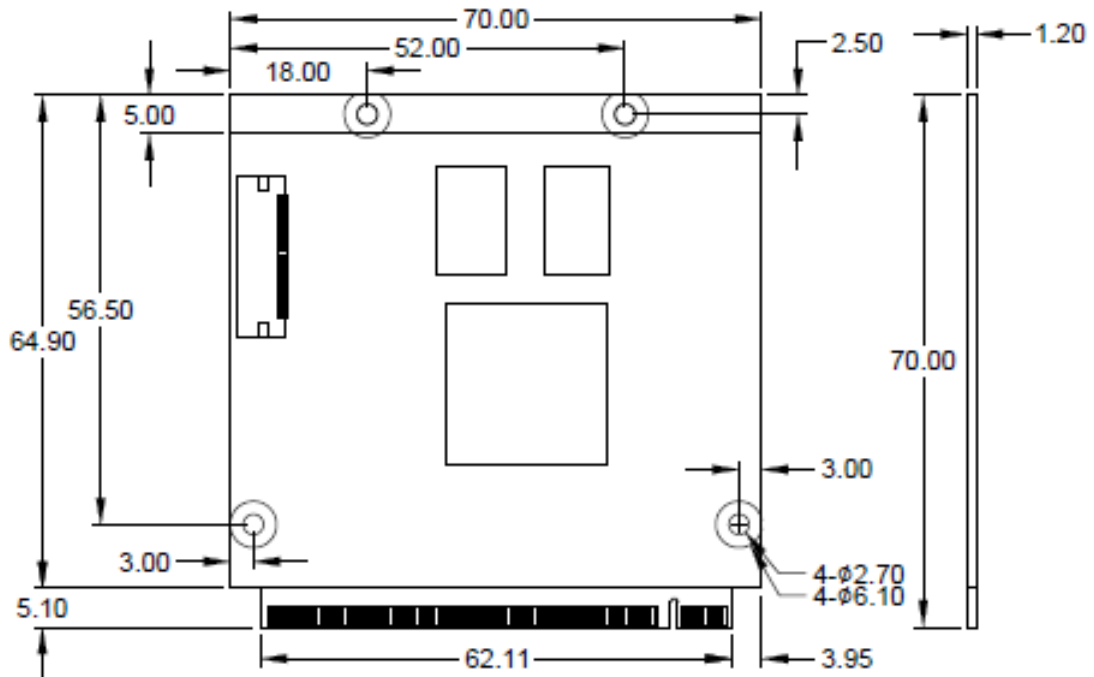


Note: *All specifications and images are subject to change without notice.*

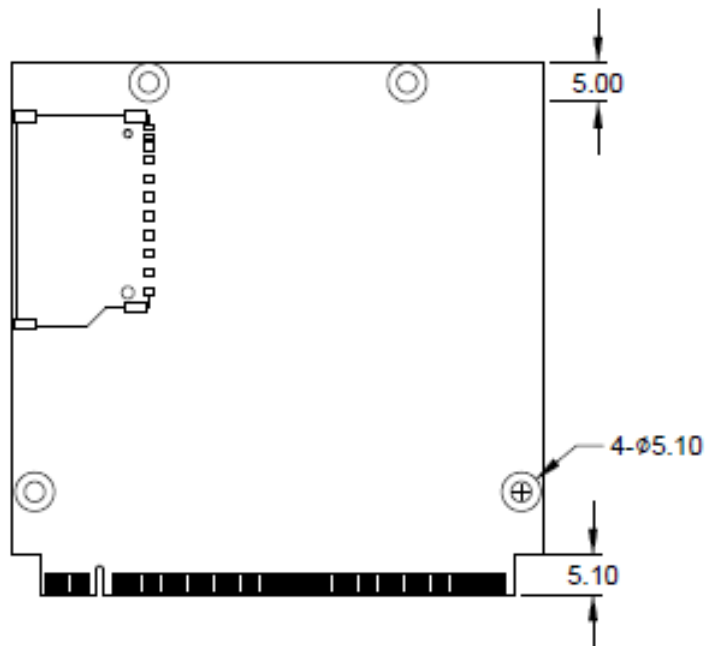
Chapter 2

Board and Pin Assignments

2.1 Board Dimensions and Fixing Holes

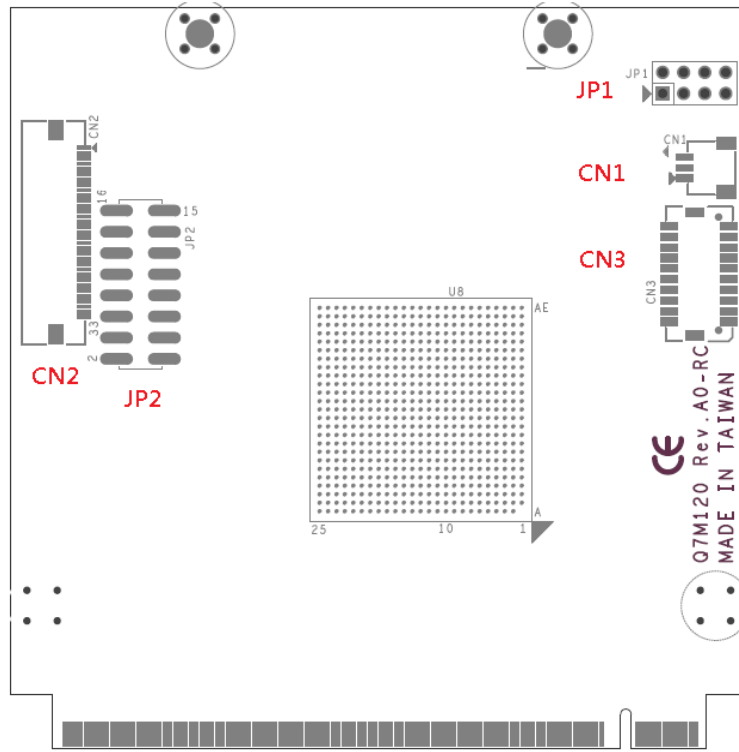


Top View

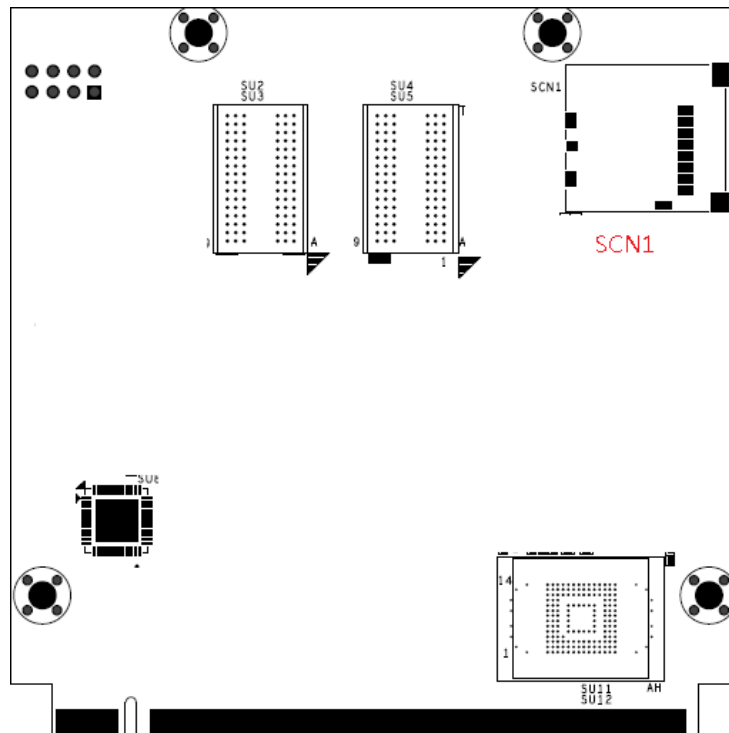


Bottom View

2.2 Board Layout



Top View



Bottom View

2.3 Installing Heatsink & Heatspreader

For thermal dissipation, the heatsink & heatspreader enable the Q7M120 components to dissipate heat efficiently. All heat generating components are thermally conducted to the heatsink or heatspreader in order to avoid hot spots. Below procedures illustrate how to install the heatsink and heatspreader on Q7M120.

2.3.1 Heatsink

1. The heatsink is designed for the Q7M120 module. Before installing the heatsink to the CPU module, please ensure that the surface of the processor is clean and free of dust and finger oil. This is especially critical for Q7M120 module that is with high CPU speed to ensure that the heatsink acts as a proper thermal interface for cooling solutions.
2. Please tear the sticker protector, place the heatsink on top of the processor chip. It makes even contact all around



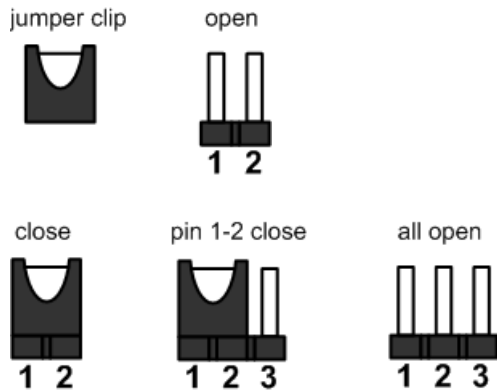
2.3.2 Heatspreader

1. The heatspreader is designed for the Q7M120 module. The thermal pad on the heatspreader is designed to make contact with the necessary components on the Q7M120 module. When mounting the heatspreader you must make sure that the thermal pads on the heatspreader make complete contact (no space between thermal pad and component) with the corresponding components on the Q7M120 module. This is especially critical for Q7M120 module that is with high CPU speed to ensure that the heat spreader acts as a proper thermal interface for cooling solutions.
2. This CPU module has four assembly holes for installing heat spreader plate. Use the four screws to secure the heat spreader plate to the Q7M120. Be careful not to over-tighten the screws



2.4 Connectors

Jumper is a small component consisting of jumper clip and jumper pins. Install jumper clip on 2 jumper pins to close. And remove jumper clip from 2 jumper pins to open. The following illustration shows how to set up jumper.



Below you can find a summary table of all jumpers and onboard default settings.

2.4.1 Boot Mode Selection (JP2)

These jumpers are for boot mode selection.

| Function | Setting |
|--|---|
| Copy image to eMMC | JP2 9-10, 11-12 Close |
| Boot to OS (Q7M120 eMMC) (Default) | JP2 1-2, 3-4 Close JP2 7-8, 11-12 Close JP2 13-14 Close |
| Boot to OS (Q7B120 SD Card) | JP2 3-4, 5-6, 13-14 Close |



2.5 Connectors

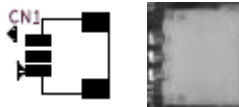
Signals go to other parts of the system through connectors. Loose or improper connection might cause problems, please make sure all connectors are properly and firmly connected. Here is a summary table which shows all connectors on the hardware.

| Connector | Description |
|-----------|----------------------|
| CN1 | Debug Port Connector |
| CN2 | 33-pin ZIF Connector |

2.5.1 Debug Port Connector (CN1)

The CN1 is a 3-pin wafer connector for TX/RX debug UART port, see table below.

| Pin | Signal |
|-----|----------|
| 1 | Debug TX |
| 2 | Debug RX |
| 3 | GND |



2.5.2 33-pin ZIF Connector (CN2)

This board has a 33-pin ZIF connector (CN2) for interfacing TTL LCD to baseboard.

| Pin | Signal | Pin | Signal |
|-----|--------------|-----|--------------|
| 1 | GND | 2 | DISP0_DAT16 |
| 3 | DISP0_DAT17 | 4 | DISP0_DAT18 |
| 5 | DISP0_DAT19 | 6 | DISP0_DAT20 |
| 7 | DISP0_DAT21 | 8 | DISP0_DAT22 |
| 9 | DISP0_DAT23 | 10 | DISP0_DAT8 |
| 11 | DISP0_DAT9 | 12 | DISP0_DAT10 |
| 13 | DISP0_DAT11 | 14 | DISP0_DAT12 |
| 15 | DISP0_DAT13 | 16 | DISP0_DAT14 |
| 17 | DISP0_DAT15 | 18 | DISP0_DAT0 |
| 19 | DISP0_DAT1 | 20 | DISP0_DAT2 |
| 21 | DISP0_DAT3 | 22 | DISP0_DAT4 |
| 23 | DISP0_DAT5 | 24 | DISP0_DAT6 |
| 25 | DISP0_DAT7 | 26 | GND |
| 27 | DISP0_CLK | 28 | DISP0_CNTRST |
| 29 | DISP0_HSYNCH | 30 | DISP0_VSYNCH |
| 31 | DISP0_DRDY | 32 | GND |
| 33 | GND | | |



2.5.3 JTAG Connector (JP1)

This board has a JTAG Connector (JP1) for interfacing JTAG ICE TOOL.

| Pin | Signal | Pin | Signal |
|-----|------------|-----|----------|
| 1 | GEN_3V3 | 2 | JTAG_TMS |
| 3 | JTAG_nTRST | 4 | JTAG_TCK |
| 5 | JTAG_TDI | 6 | JTAG_TDO |
| 7 | GND | 8 | POR_B |

2.5.4 20-pin Connector (CN3)

This board has a 20-pin connector (CN3) for interfacing to MIPI camera module.

| Pin | Signal | Pin | Signal |
|-----|-------------|-----|-----------|
| 1 | GPIO_0_CLKO | 2 | PMIC_5V |
| 3 | CSI_RST_B | 4 | GND |
| 5 | INC_CSI_D2M | 6 | CSI_D1P |
| 7 | INC_CSI_D2P | 8 | CSI_D1M |
| 9 | GND | 10 | GND |
| 11 | INC_CSI_D3M | 12 | CSI_D0P |
| 13 | INC_CSI_D3P | 14 | CSI_D0M |
| 15 | GND | 16 | GND |
| 17 | I2C2_SCL | 18 | CSI_CLK0P |
| 19 | I2C2_SDA | 20 | CSI_CLK0M |
| 21 | NC | 22 | NC |
| 23 | NC | 24 | NC |